## **MA3S781F**

### Silicon epitaxial planar type

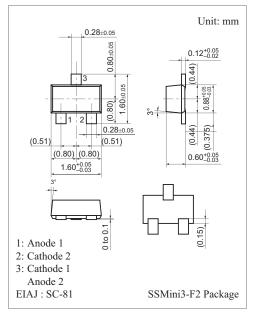
For high speed switching circuits

#### ■ Features

- Optimum for high-density mounting
- ullet Short reverse recovery time  $t_{rrr}$ , optimum for high-frequency rectification

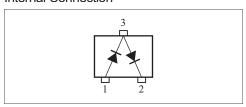
#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Reverse voltage	V <sub>R</sub> 30		V		
Maximum peak reverse voltage		V <sub>RM</sub> 30		V	
Forward current	Single	Ţ	30	mA	
	Series	$I_{\rm F}$	20		
Peak forward current	Single	т	150	mA	
	Series	$I_{FM}$	110		
Junction temperature		T <sub>j</sub>	T <sub>j</sub> 125		
Storage temperature		T <sub>stg</sub>	-55 to +125	°C	



#### Marking Symbol: M1U

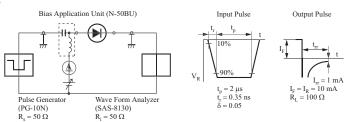
#### Internal Connection



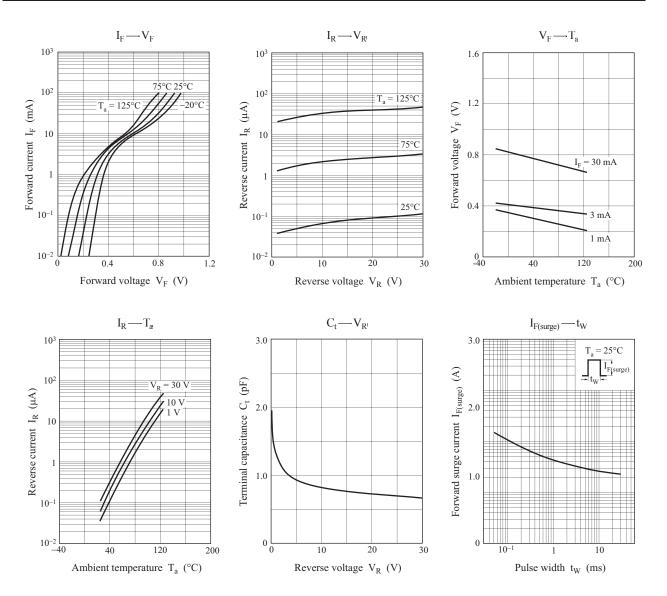
#### ■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{Fl}$	$I_F = 1 \text{ mA}$			0.4	V
	$V_{F2}$	$I_F = 30 \text{ mA}$			1.0	
Reverse current	$I_R$	$V_{Rl} = 30 \text{ V}$			300	nA
Terminal capacitance	$C_{t}$	$V_{Rl} = 1 \text{ V, } f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_{Rl} = 10 \text{ mA}, I_{rr} = 1 \text{ mA}$ $R_{Ll} = 100 \Omega$		1.0		ns
Detection efficiency	η	$V_{IN^1} = 3 V_{(peak)}$ , f = 30 MHz $R_{LI} = 3.9 \text{ k}\Omega$ , $C_{LI} = 10 \text{ pF}$		65		%

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. Absolute frequency of input and output is  $2\,000\ \text{MHz}$
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*:  $t_{rr}$  measurement circuit



MA3S781F Panasonic



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